MSKSEMI















ESD

TVS

TSS

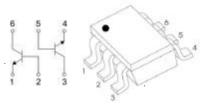
MOV

GDT

PLED

Brodnet data speet

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SOT-363

DUAL TRANSISTOR (NPN+NPN)

APPLICATION

This device is designed for general purpose amplifier applications

MARK:1Ft

MAXIMUM RATINGS (T₂=25°C unless otherwise noted)

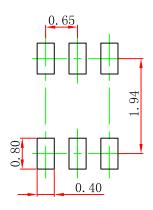
Symbol	Parameter	Value	Unit	
Vсво	Collector-Base Voltage 50			
Vceo	Collector-Emitter Voltage	45	V	
VEBO	Emitter-Base Voltage	6		
lc	Collector Current-Continuous	100	mA	
Po	Power Dissipation	200	mW	
Reja	Thermal Resistance. Junction to Ambient	625	°C/W	
Tj	Junction Temperature	150		
Tstg	Storage Temperature Range	-55~+150	℃	

ELECTRICAL CHARACTERISTICS (Ta=25°C unless otherwise specified)

Parameter	Symbol	Test conditions		Min	Тур	Max	Unit	
Collector-base breakdown voltage	V(BR)CBO	Ic=10μA,Iε=0		50			V	
Collector-emitter breakdown voltage	V(BR)CEO	I _C =1mA,I _B =0		45			V	
Emitter-base breakdown voltage	V(BR)EBO	I _E =10μA,I _C =0		6			V	
Collector cut-off current	Ісво	V _{CB} =30V,I _E =0				15	nA	
Emitter cut-off current	I _{EBO}	V _{EB} =4V, I _C =0				15	IIA	
DC current gain*	h _{FE}	V _{CE} =5V,I _C =2mA	4	110		220		
		l I	В	200		450		
			С	420		800		
Collector omitter acturation voltage	VCE(sat)(1)	Ic=10mA,I _B =0.5mA				0.25	V	
Collector-emitter saturation voltage	VCE(sat)(2)	Ic=100mA,I _B =5mA				0.65	V	
Page emitter veltage	VBE(1)	V _{CE} =5V,I _C =2mA		0.58		0.7	V	
Base-emitter voltage	VBE(2)	V _{CE} =5V,I _C =10mA				0.77	V	
Transition frequency	f⊤	V _{CE} =5V,I _C =20mA ,f=100MHz			200		MHz	
Collector output capacitance	Cob	V _{CB} =10V,I _E =0,f=1MHz			2		pF	

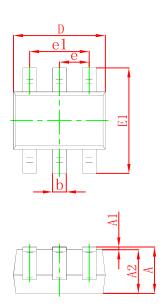
^{*}pulse test: Pulse Width ≤300µs, Duty Cycle≤ 2.0%.

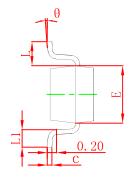
SOT-363



Note:

- 1.Controlling dimension:in millimeters. 2.General tolerance:± 0.05mm.
- 3. The pad layout is for reference purposes only.





Symbol	Dimensions In Millimeters		Dimensions In Inches		
Syllibol	Min	Max	Min	Max	
Α	0.900	1.100	0.035	0.043	
A1	0.000	0.100	0.000	0.004	
A2	0.900	1.000	0.035	0.039	
b	0.150	0.350	0.006	0.014	
С	0.100	0.150	0.004	0.006	
D	2.000	2.200	0.079	0.087	
Е	1.150	1.350	0.045	0.053	
E1	2.150	2.400	0.085	0.094	
е	0.650 TYP		0.026 TYP		
e1	1.200	1.400	0.047	0.055	
L	0.525 REF		0.021 REF		
L1	0.260	0.460	0.010	0.018	
θ	0°	8°	0°	8°	

REEL SPECIFICATION

P/N	PKG	QTY
BC847S	SOT-363	3000



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